

Specifications

Insulation Resistance

Aliases (C1206X103KFRAC7800) SMD Comm X7R HV Flex, Ceramic, 0.01 uF, 10%, 1,500 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 1206, 1.5 mm



| General Information | |
|--------------------------|--|
| Series | SMD Comm X7R HV Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, FT-CAP, Temperature Stable |
| Features | FT-CAP, Temperature Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 55 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|-----------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| Т | 1.6mm +/-0.25mm |
| S | 1.5mm MIN |
| В | 0.6mm +/-0.25mm |
| | |

| Capacitance | 0.01 uF |
|--|--|
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 1500 VDC |
| Dielectric Withstanding Voltage | 1,800 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 2.5%1kHz1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |

100 GOhms

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 2000 |

| Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and |
|--|
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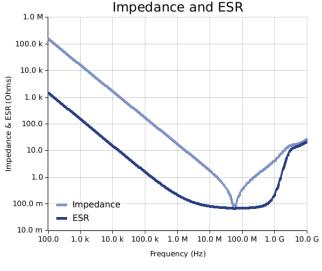
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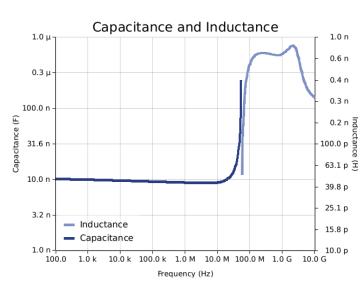


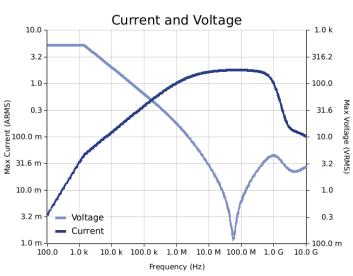
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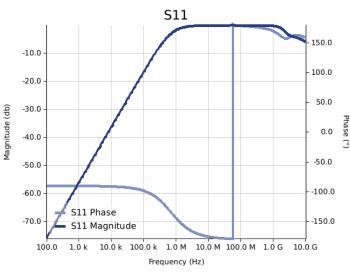
Simulations

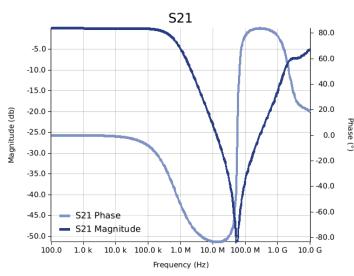
For the complete simulation environment please visit K-SIM.

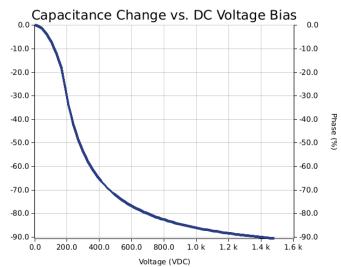










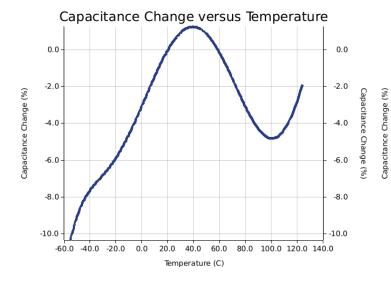


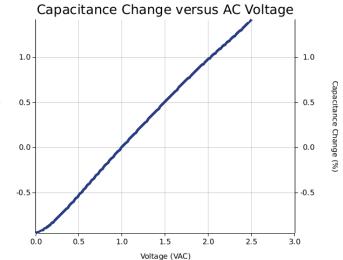
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Phase (%)



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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is unleast at an interact temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.

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